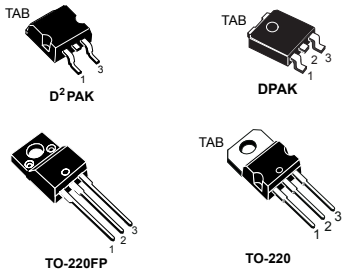
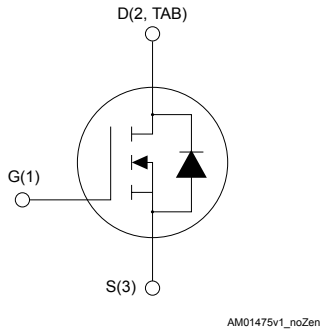
STB11N65M5, STD11N65M5
STF11N65M5, STP11N65M5

Datasheet

N-channel 650 V, 430 mΩ typ., 9 A MDmesh M5 Power MOSFETs in D²PAK, DPAK, TO-220FP and TO-220 packages





Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STB11N65M5	650 V	480 mΩ	9 A
STD11N65M5			
STF11N65M5			
STP11N65M5			

- 100% avalanche tested
- Excellent switching performance
- Extremely low $R_{DS(on)}$
- Low gate charge and input capacitance

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs based on the MDmesh M5 innovative vertical process technology combined with the well-known PowerMESH horizontal layout. The resulting products offer extremely low on-resistance, making them particularly suitable for applications requiring high power and superior efficiency.

Product status links
STB11N65M5
STD11N65M5
STF11N65M5
STP11N65M5

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		D^2PAK DPAK TO-220	TO-220FP	
V_{GS}	Gate-source voltage	±25		V
I_D	Drain current (continuous) at T_C = 25 °C	9	9(1)	A
I_D	Drain current (continuous) at T_C = 100 °C	5.6	5.6(1)	A
I_{DM}(2)	Drain current (pulsed)	36	36(1)	A
P_{TOT}	Total power dissipation at T_C = 25 °C	85	25	W
dv/dt(3)	Peak diode recovery voltage slope	15		V/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T_c = 25 °C)	-	2.5	kV
T_J	Operating junction temperature range	-55 to 150		°C
T_{stg}	Storage temperature range			

1. *Limited by maximum junction temperature.*
2. *Pulse width limited by safe operating area.*
3. *I_{SD} ≤ 9 A, di/dt ≤ 400 A/µs; V_{DS} (peak) < $V_{(BR)DSS}$, V_{DD} = 400 V.*

Table 2. Thermal data

Symbol	Parameter	Value				Unit
		D^2PAK	DPAK	TO-220FP	TO-220	
R_{thJC}	Thermal resistance, junction-to-case	1.47		5.0	1.47	°C/W
R_{thJA}	Thermal resistance, junction-to-ambient	30(1)	50(1)	62.5		°C/W

1. *When mounted on a standard 1 inch^2 area of FR-4 PCB with 2-oz copper.*

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J max.)	2	A
E_{AS}	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	130	mJ

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	I_D = 1 mA, V_{GS} = 0 V	650	-	-	V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 650 V	-	-	1	µA
		V_{GS} = 0 V, V_{DS} = 650 V, T_C = 125 °C(1)	-	-	100	µA
I_{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V	-	-	±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS} = 10 V, I_D = 4.5 A	-	430	480	mΩ

1. *Specified by design, not tested in production.*

Table 5. Dynamic

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 100 V, f = 1 MHz, V_{GS} = 0 V	-	644	-	pF
C_{oss}	Output capacitance			18		pF
C_{rss}	Reverse transfer capacitance			2.5		pF
$C_{o(tr)}$(1)	Equivalent capacitance time related	V_{DS} = 0 to 520 V, V_{GS} = 0 V	-	55	-	pF
$C_{o(er)}$(2)	Equivalent capacitance energy related		-	17	-	pF
Rg	Gate input resistance	f = 1 MHz open drain	-	5	-	Ω
Q_g	Total gate charge	V_{DD} = 520 V, I_D = 4.5 A, V_{GS} = 0 to 10 V (see the Figure 19. Test circuit for gate charge behavior)	-	17	-	nC
Q_{gs}	Gate-source charge			4.6		nC
Q_{gd}	Gate-drain charge			8.5		nC

1. *Time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*
2. *Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*

Table 6. Switching times

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$t_{d(v)}$	Voltage delay time	V_{DD} = 400 V, I_D = 7.5 A, R_G = 4.7 Ω, V_{GS} = 10 V (see the Figure 20. Test circuit for inductive load switching and diode recovery times and Figure 23. Switching time waveform)	-	23	-	ns
$t_{r(v)}$	Voltage rise time			10		ns
$t_{c(off)}$	Crossing time			13		ns
$t_{f(i)}$	Fall time			13.5		ns

Table 7. Source drain diode

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-	-	9	A
I_{SDM} (1)	Source-drain current (pulsed)				36	
V_{SD} (2)	Forward on voltage	I_{SD} = 9 A, V_{GS} = 0 V	-	-	1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 9 A, di/dt = 100 A/µs	-	232	-	ns
Q_{rr}	Reverse recovery charge	V_{DD} = 100 V (see the Figure 20. Test circuit for inductive load switching and diode recovery times)		2		µC
I_{RRM}	Reverse recovery current			17.5		A
t_{rr}	Reverse recovery time	I_{SD} = 9 A, di/dt = 100 A/µs	-	328	-	ns
Q_{rr}	Reverse recovery charge	V_{DD} = 100 V, Tj = 150 °C		2.8		µC
I_{RRM}	Reverse recovery current	(see the Figure 20. Test circuit for inductive load switching and diode recovery times)		17		A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics curves

Figure 1. Safe operating area for DPAK

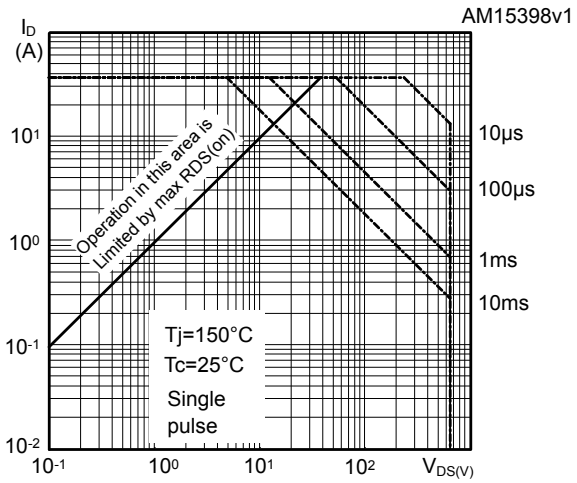


Figure 2. Thermal impedance for DPAK

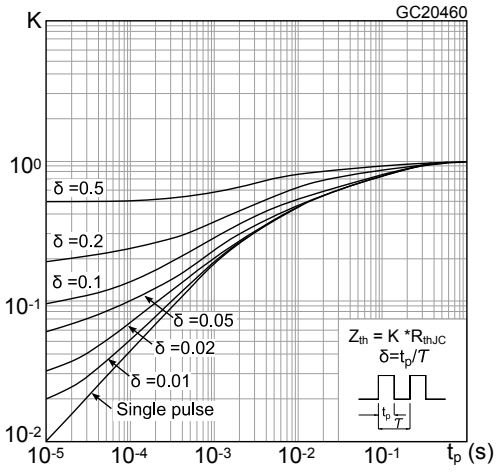


Figure 3. Safe operating area for TO-220FP

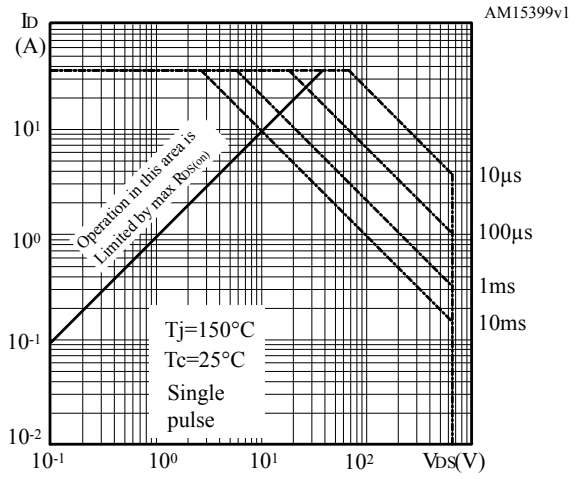


Figure 4. Thermal impedance for TO-220FP

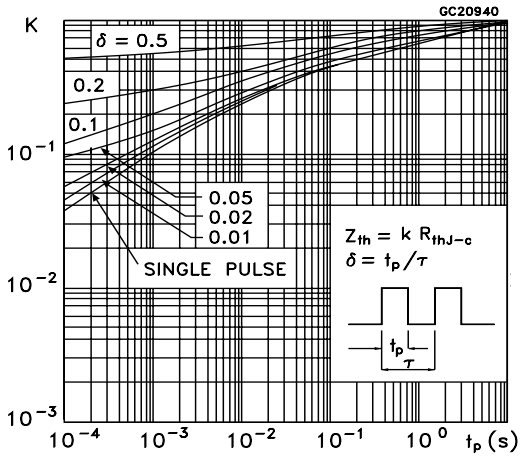


Figure 5. Safe operating area for TO-220 and D²PAK

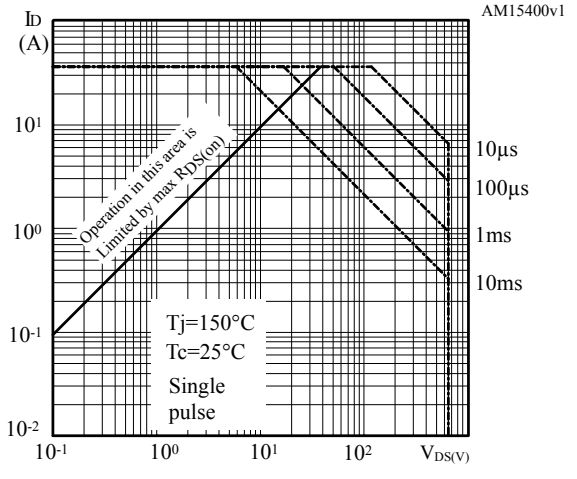


Figure 6. Thermal impedance for TO-220 and D²PAK

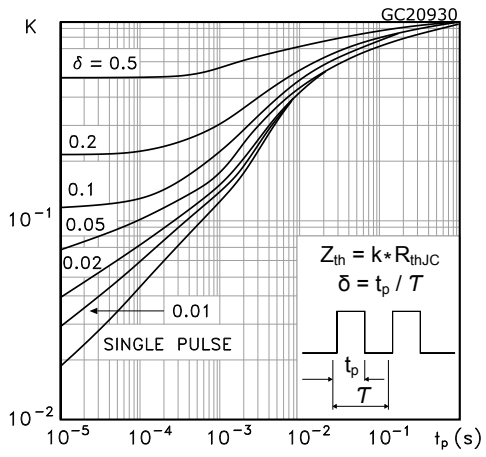


Figure 7. Output characterisics

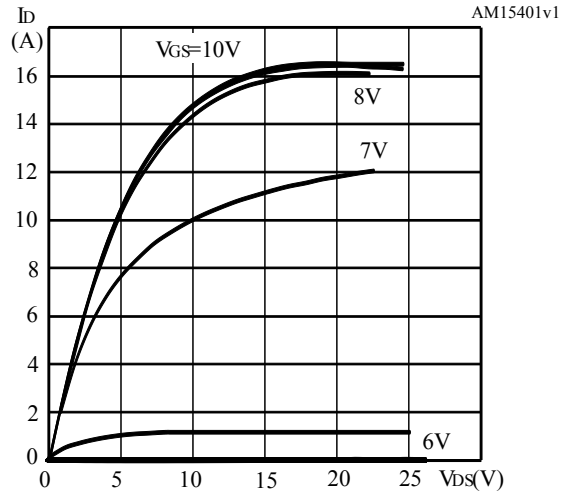


Figure 8. Transfer characteristics

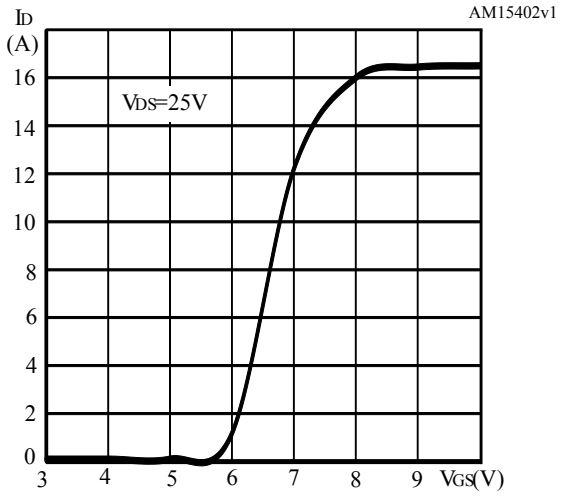


Figure 9. Gate charge vs gate-source voltage

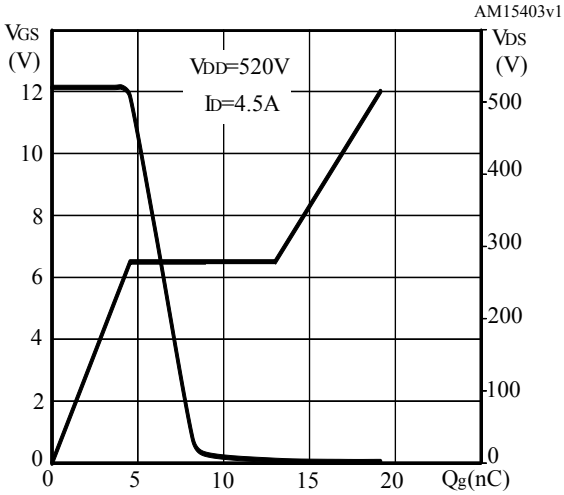


Figure 10. Static drain-source on resistance

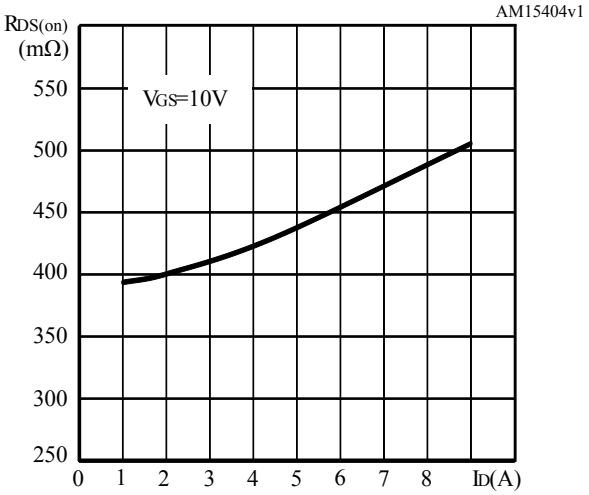


Figure 11. Capacitance variations

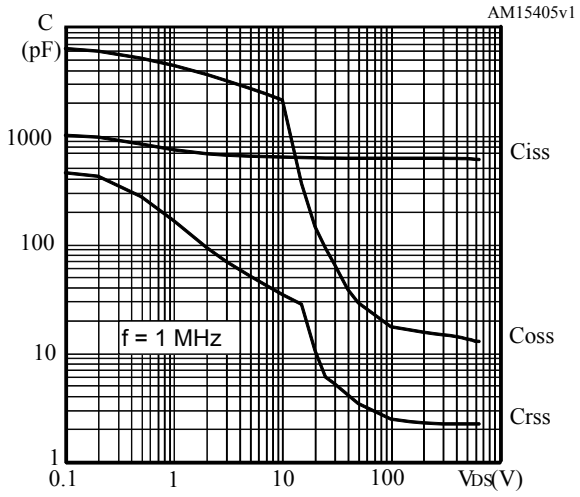


Figure 12. Output capacitance stored energy

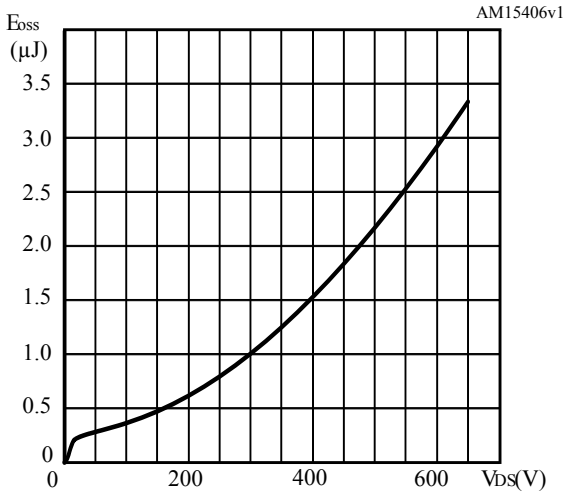


Figure 13. Normalized on-resistance vs temperature

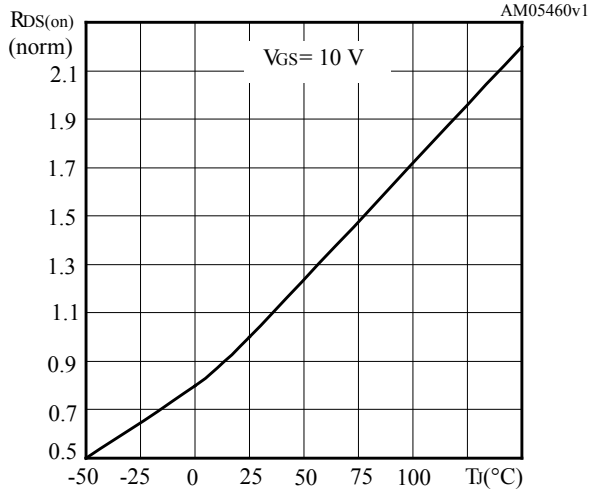


Figure 14. Normalized gate threshold voltage vs temperature

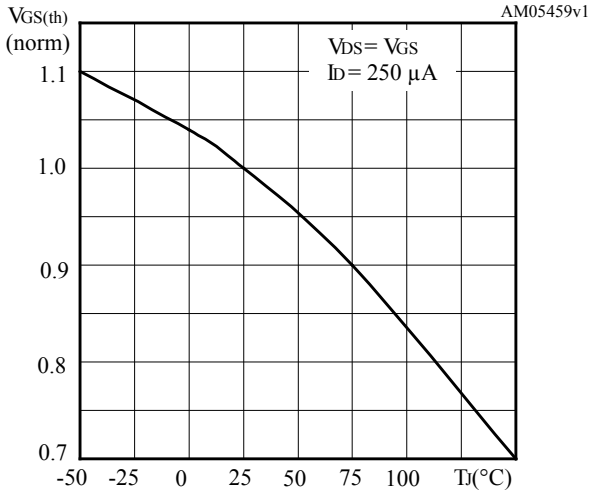


Figure 15. Drain-source diode forward characteristics

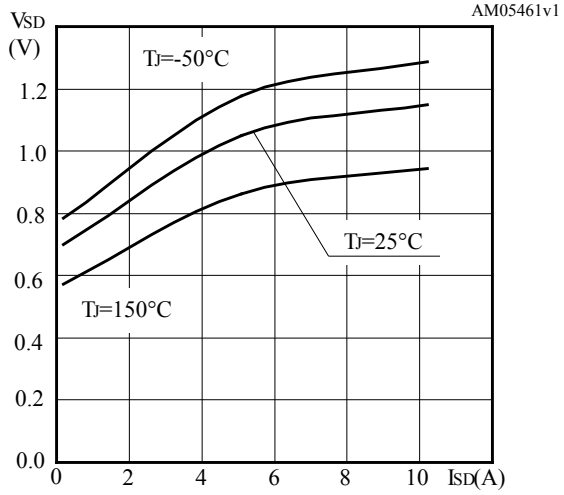


Figure 16. Normalized $V_{(BR)DSS}$ vs temperature

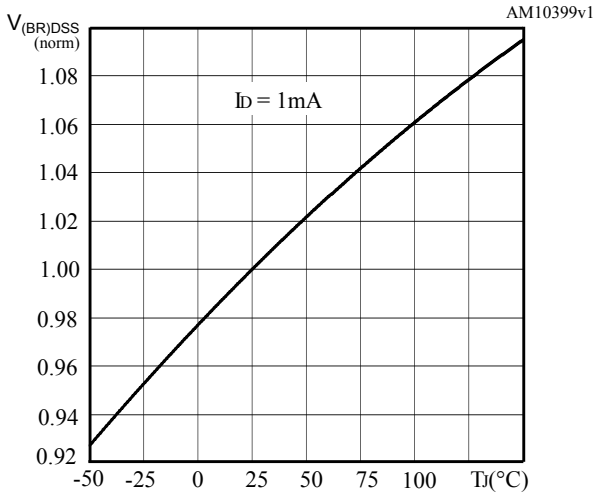
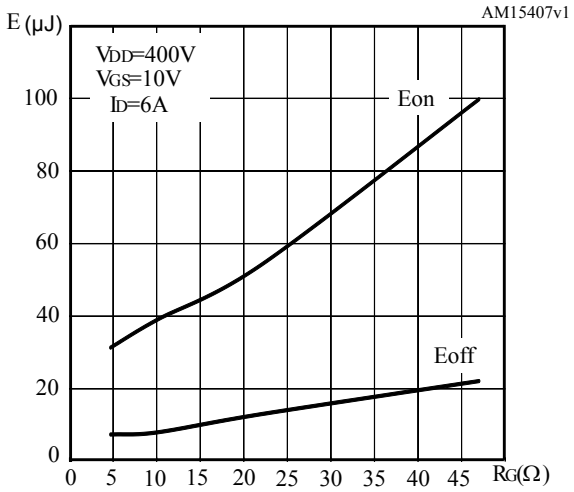
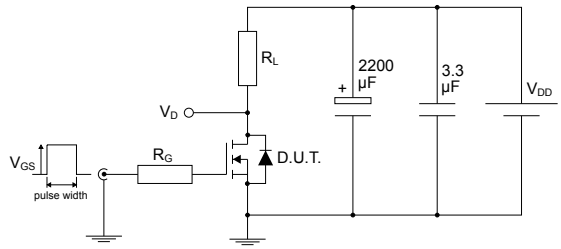


Figure 17. Switching energy vs gate resistance



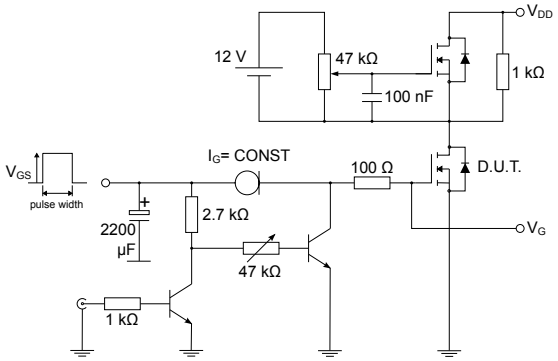
3 Test circuits

Figure 18. Test circuit for resistive load switching times



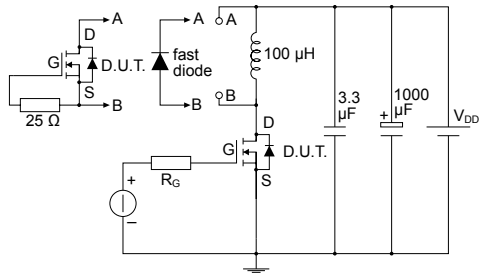
AM01468v1

Figure 19. Test circuit for gate charge behavior



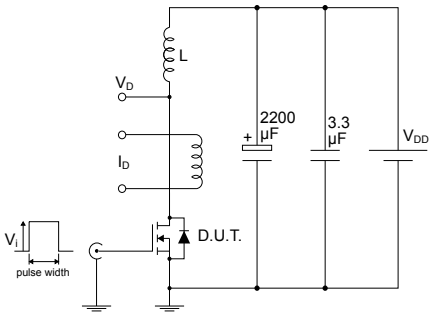
AM01469v1

Figure 20. Test circuit for inductive load switching and diode recovery times



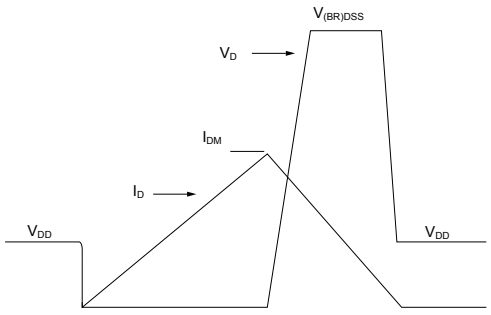
AM01470v1

Figure 21. Unclamped inductive load test circuit



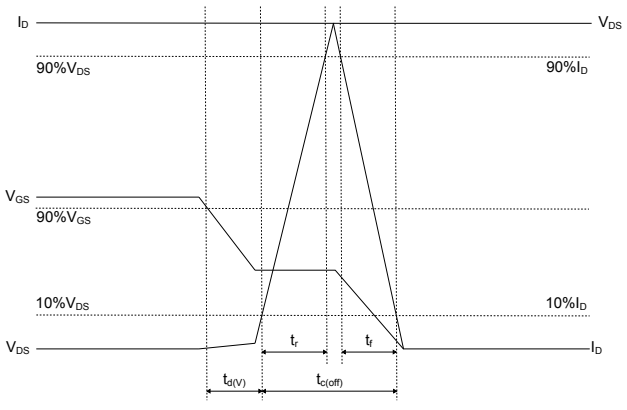
AM01471v1

Figure 22. Unclamped inductive waveform



AM01472v1

Figure 23. Switching time waveform



AM05540v2

4 Package information

To meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A package information

Figure 24. **D²PAK (TO-263) type A package outline**

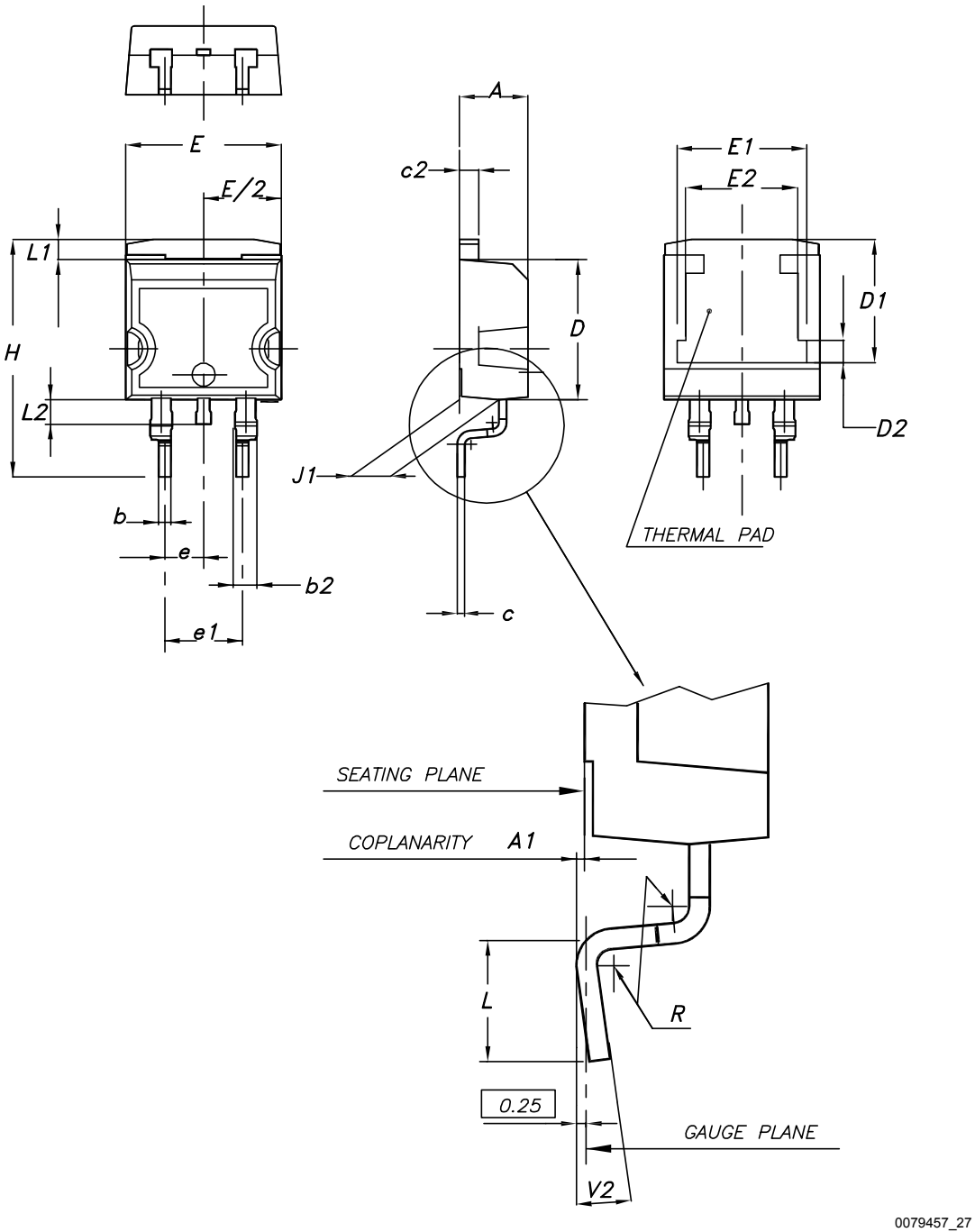
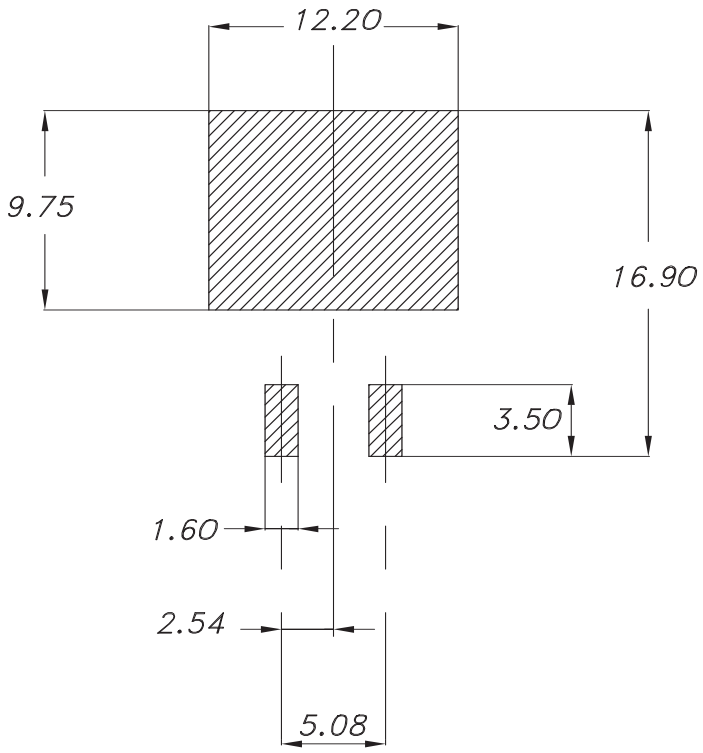


Table 8. D²PAK (TO-263) type A package mechanical data

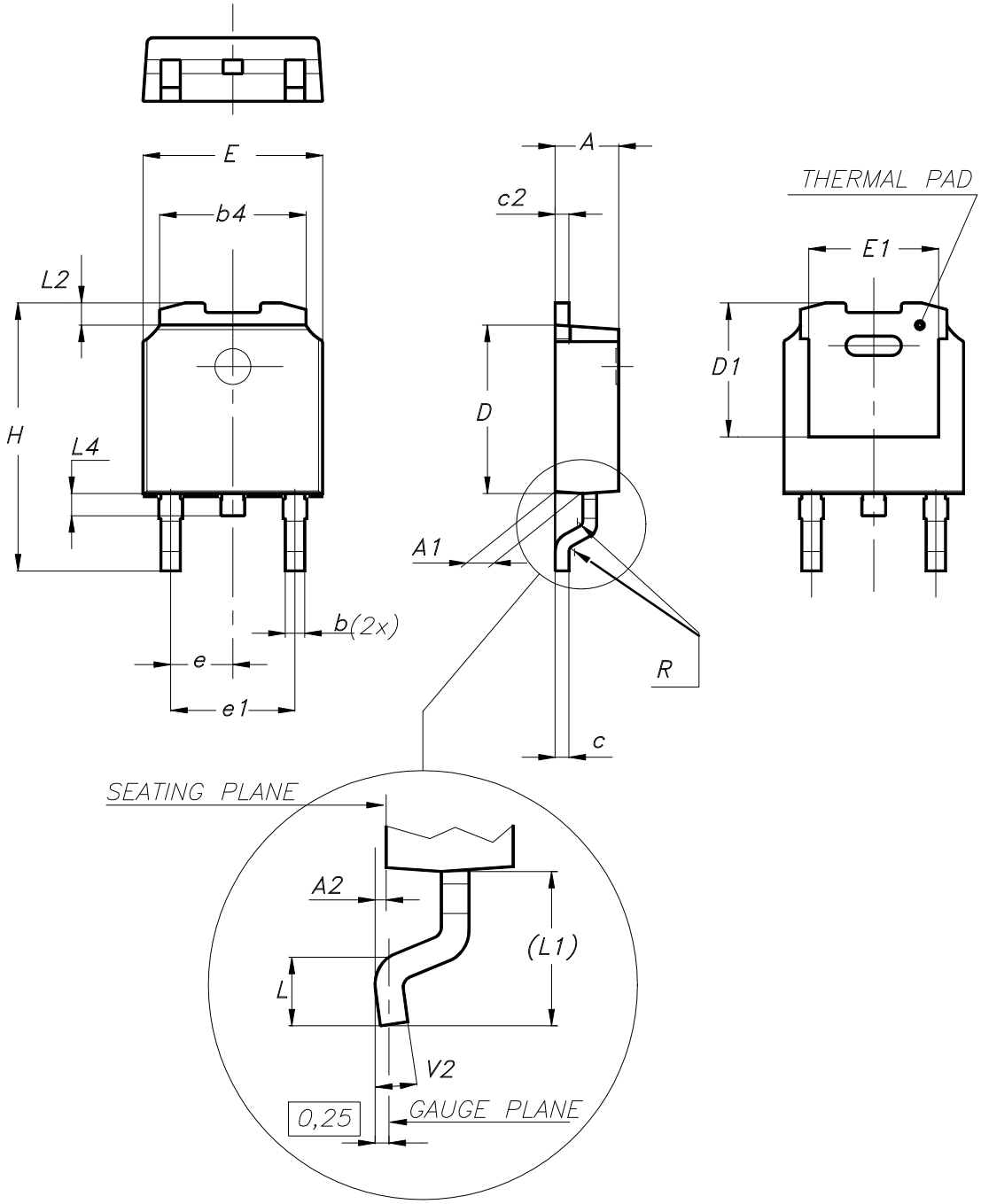
Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

Figure 25. D²PAK (TO-263) recommended footprint (dimensions are in mm)



4.2 DPAK (TO-252) type A package information

Figure 26. **DPAK (TO-252) type A package outline**



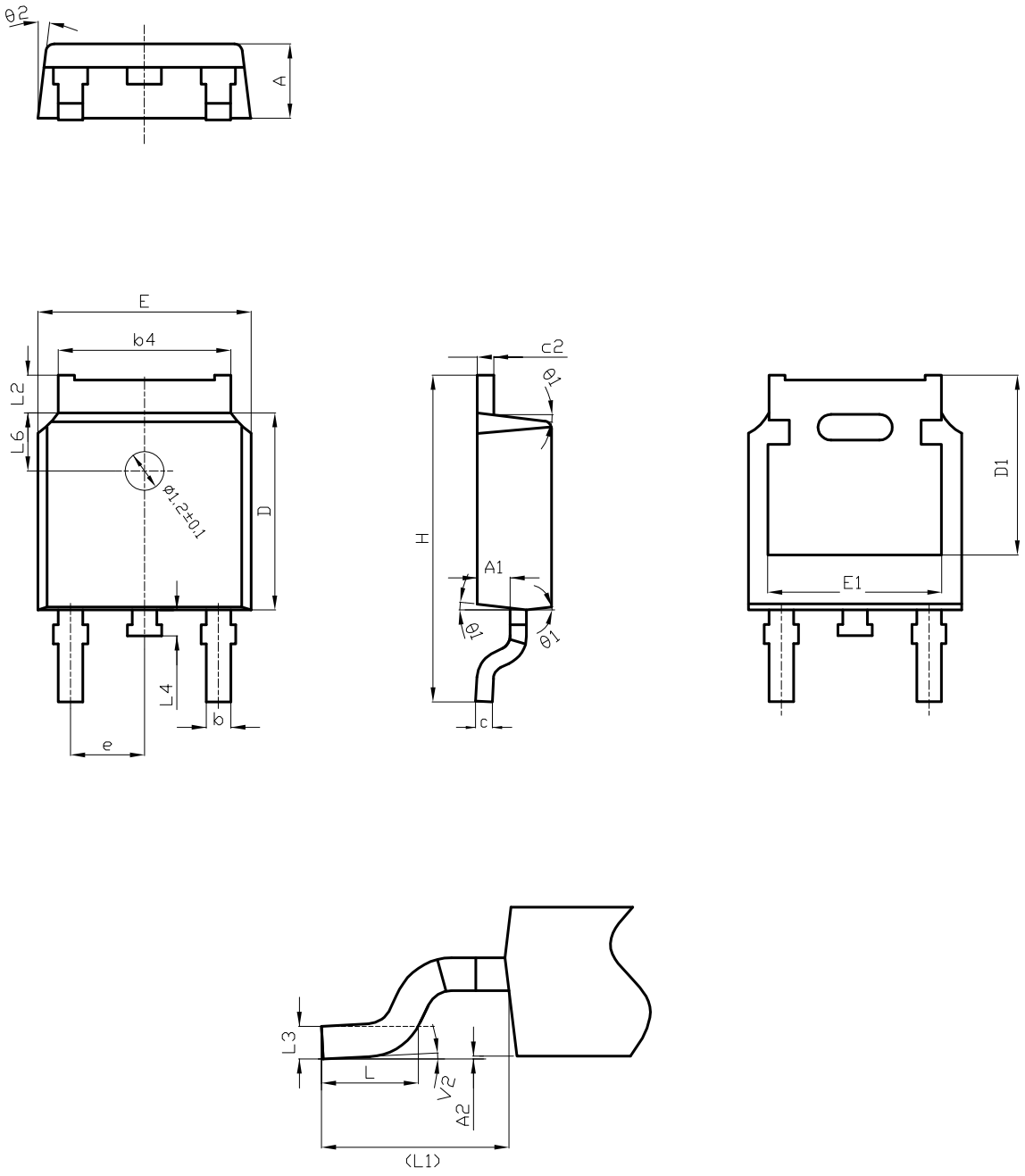
0068772_A_36

Table 9. **DPAK (TO-252) type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

4.3 DPAK (TO-252) type C2 package information

Figure 27. **DPAK (TO-252) type C2 package outline**



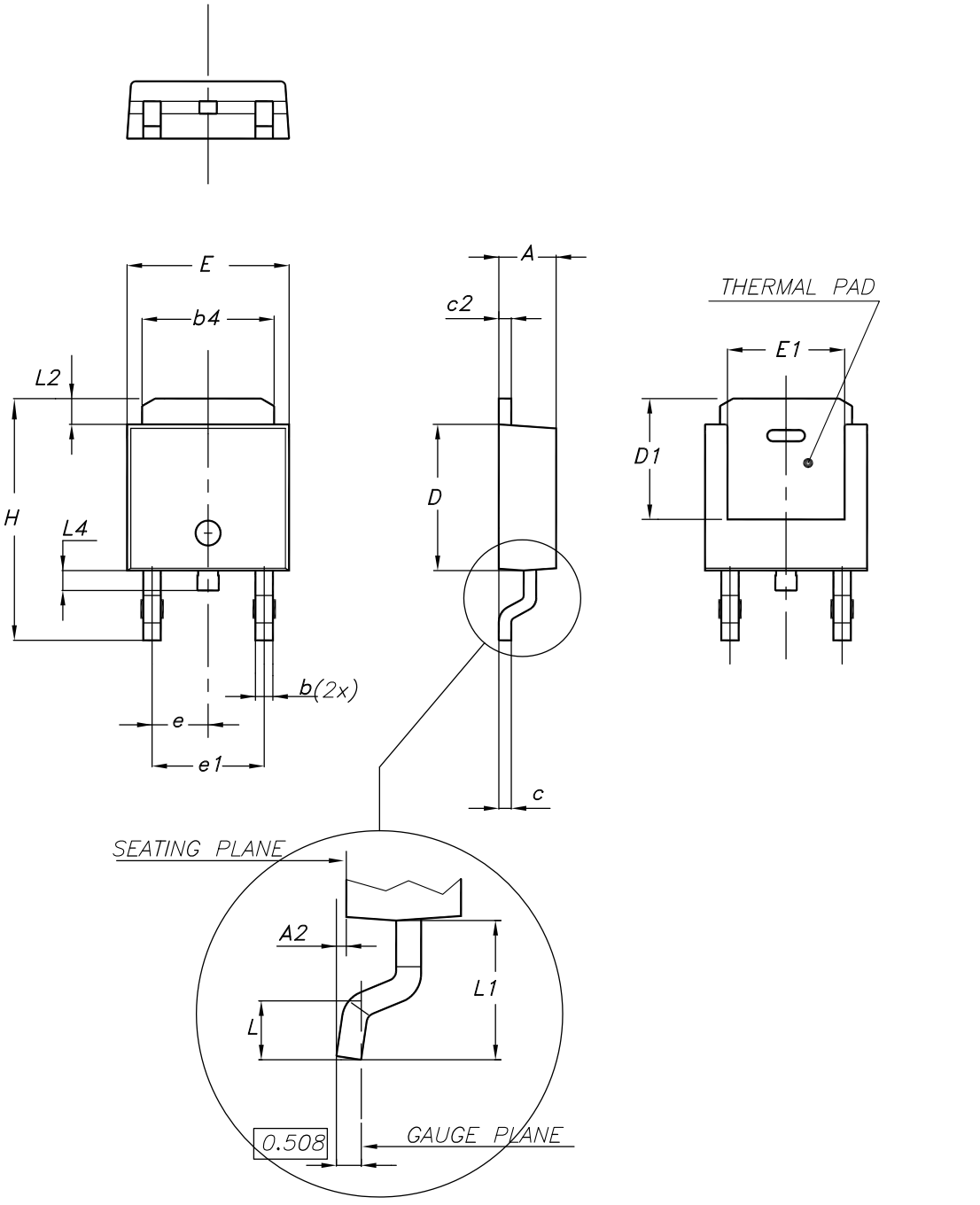
0068772_type-C2_rev36

Table 10. **DPAK (TO-252) type C2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20		5.50
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

4.4 DPAK (TO-252) type E package information

Figure 28. **DPAK (TO-252) type E package outline**

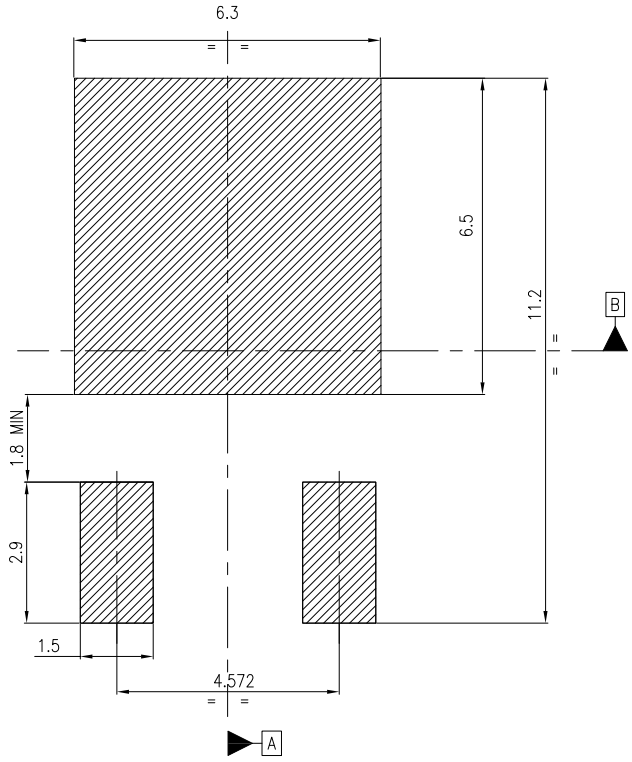


0068772_typeE_rev.36

Table 11. **DPAK (TO-252) type E mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.18		2.39
A2			0.13
b	0.65		0.884
b4	4.95		5.46
c	0.46		0.61
c2	0.46		0.60
D	5.97		6.22
D1	5.21		
E	6.35		6.73
E1	4.32		
e		2.286	
e1		4.572	
H	9.94		10.34
L	1.50		1.78
L1		2.74	
L2	0.89		1.27
L4			1.02

Figure 29. DPAK (TO-252) recommended footprint (dimensions are in mm)

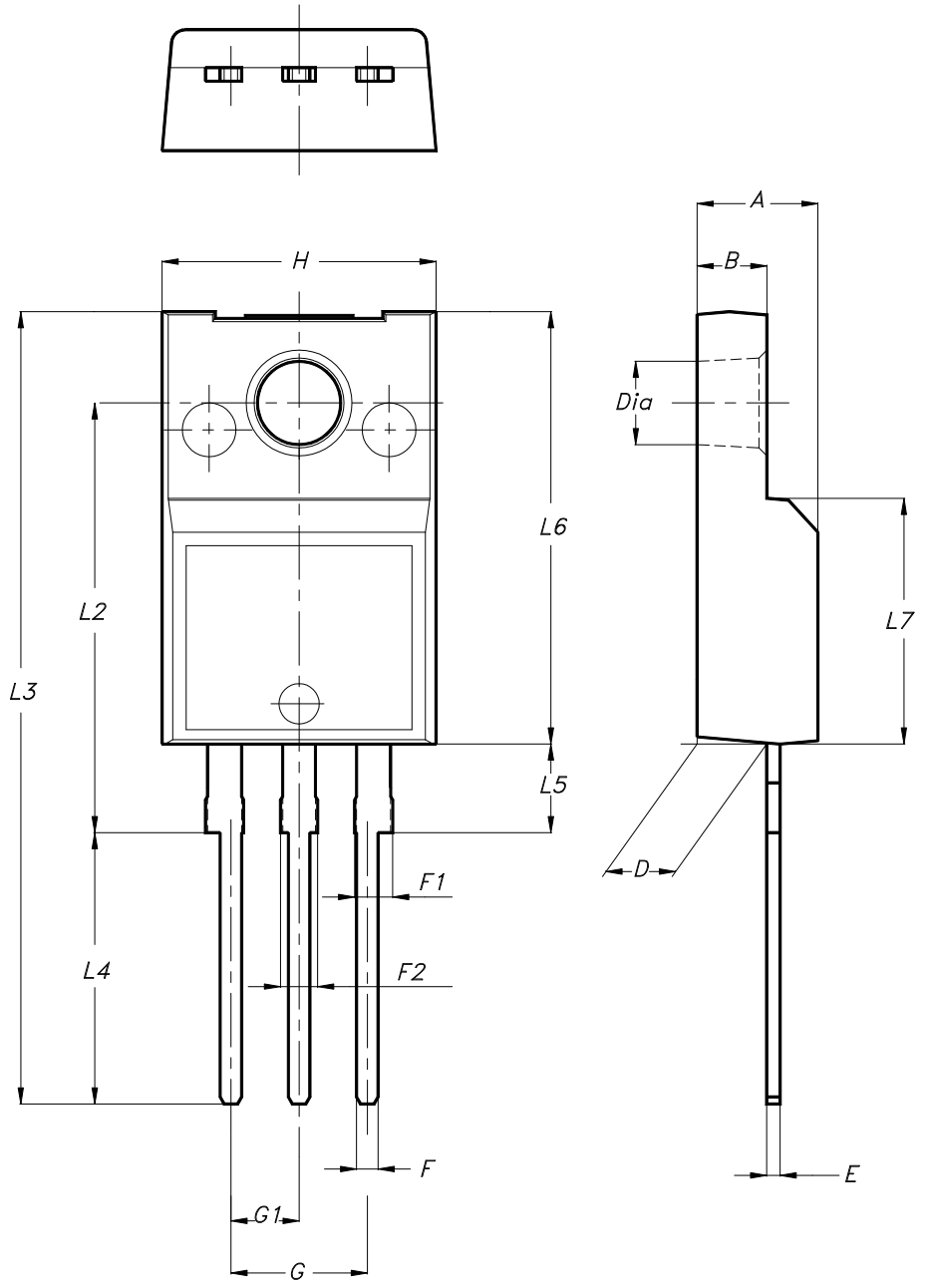


Notes:
1) This footprint is able to ensure insulation up to 630 Vrms (according to CEI IEC 664−1)
2) The device must be positioned within ⌖ 0.05 A B

FP_0068772_36

4.5 TO-220FP type B package information

Figure 30. **TO-220FP type B package outline**



7012510_B_rev.14

Table 12. **TO-220FP type B package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.6 TO-220 type A package information

Figure 31. **TO-220 type A package outline**

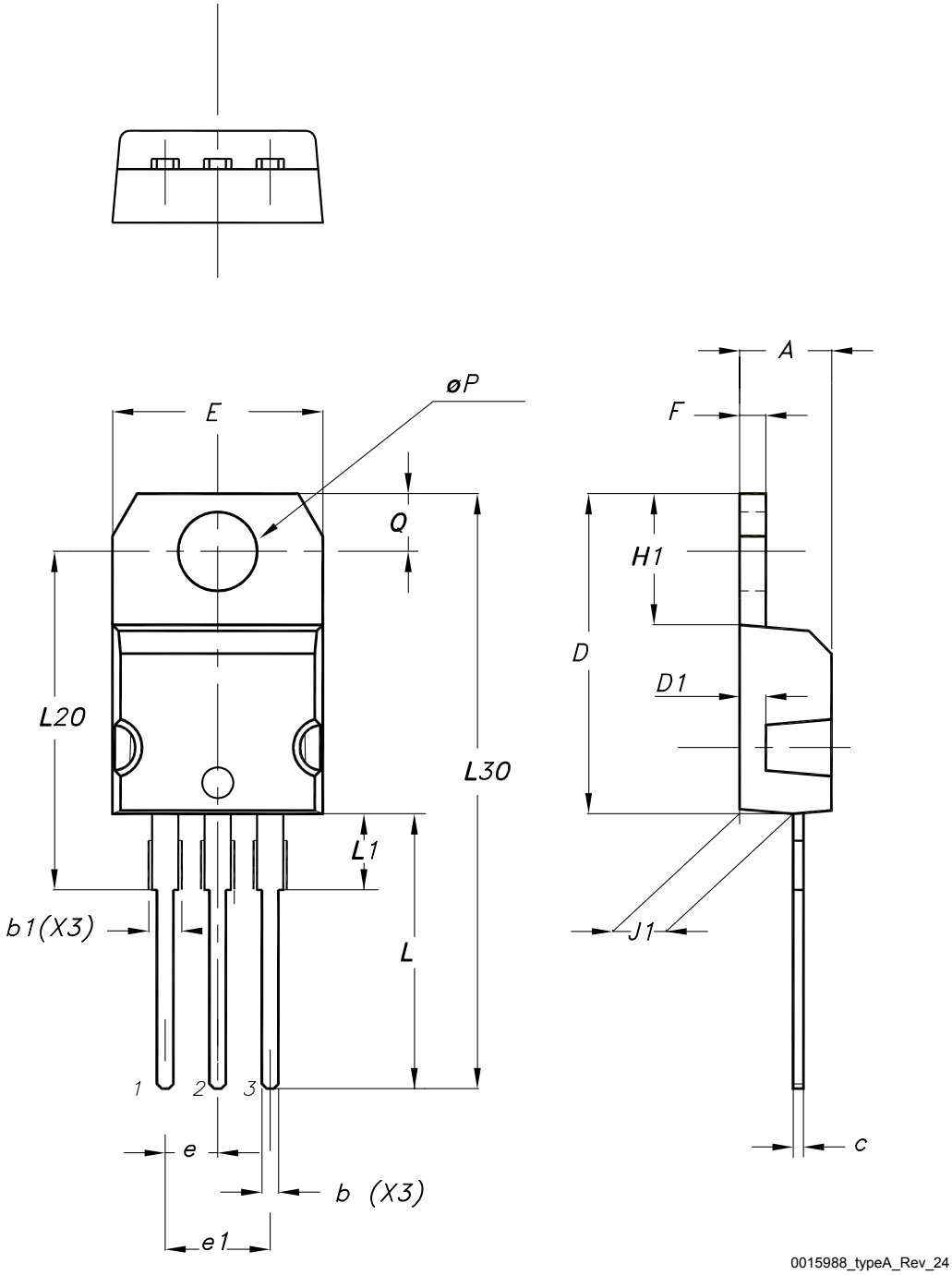
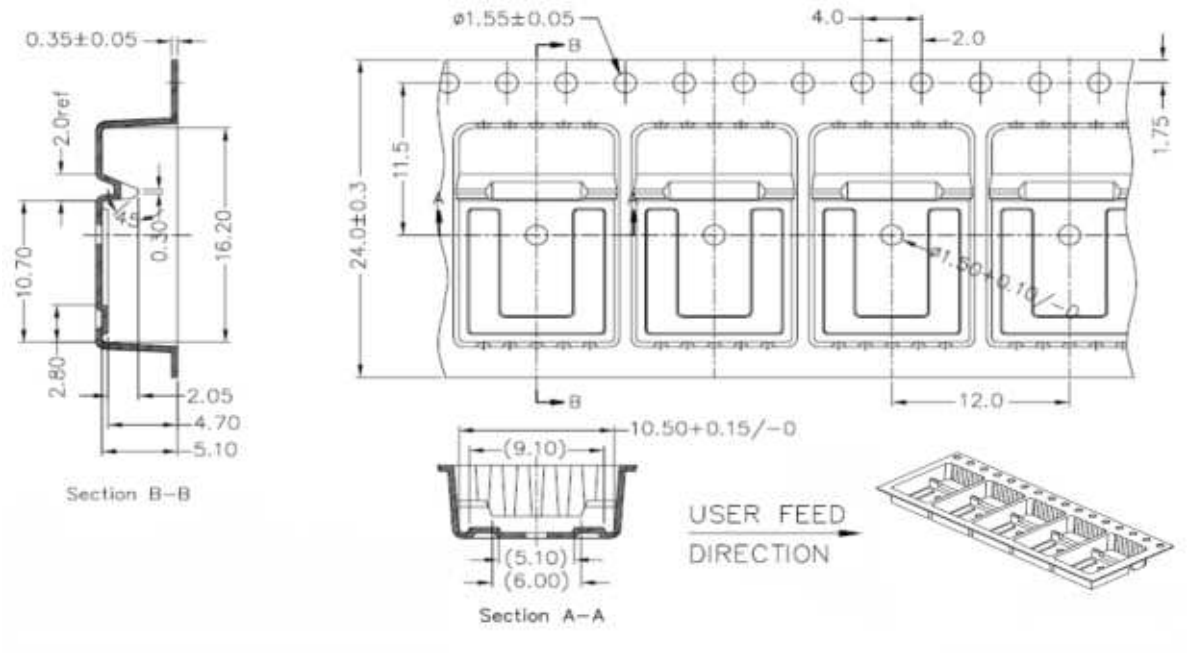


Table 13. **TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

4.7 D²PAK packing information

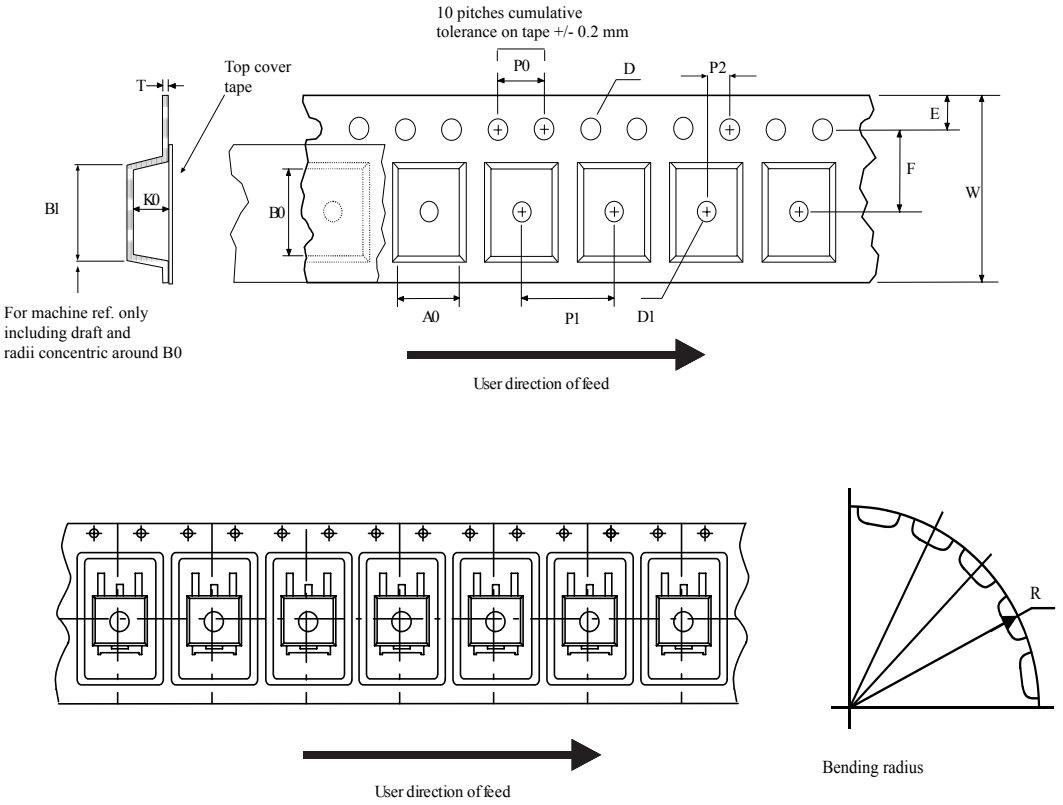
Figure 32. **D²PAK tape drawing (dimensions are in mm)**



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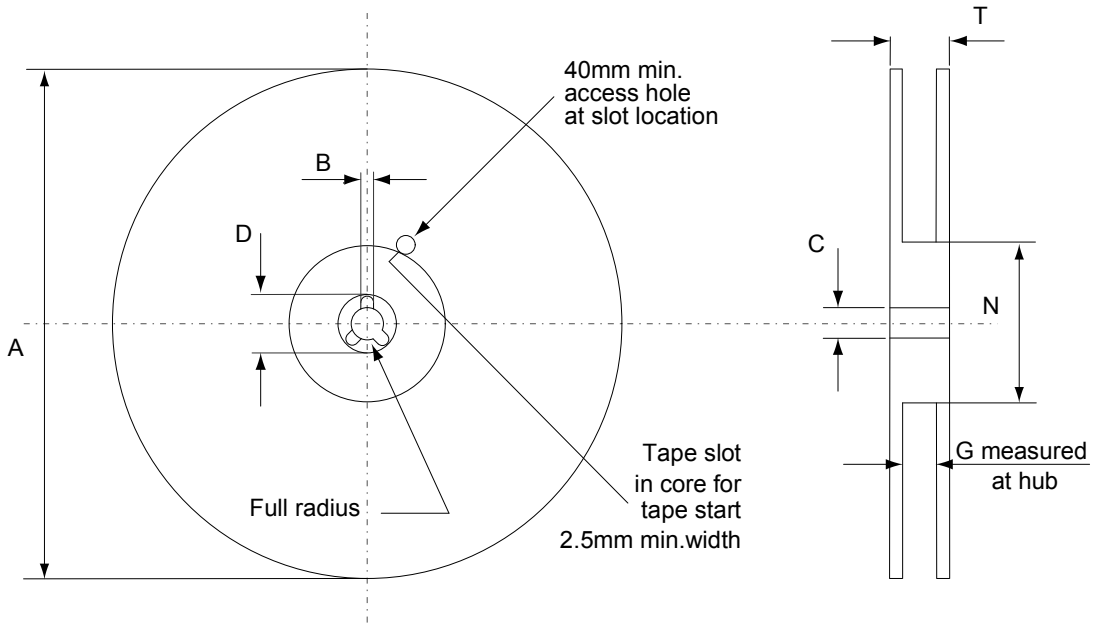
4.8 DPAK (TO-252) packing information

Figure 33. **DPAK (TO-252) tape outline**



AM08852v1

Figure 34. **DPAK (TO-252) reel outline**



AM06038v1

Table 14. **DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

5 Ordering information

Table 15. **Order codes**

Order codes	Marking	Package	Packing
STB11N65M5	11N65M5	D²PAK	Tape and reel
STD11N65M5		DPAK	
STF11N65M5		TO-220FP	Tube
STP11N65M5		TO-220	

Revision history

Table 16. **Document revision history**

Date	Version	Changes
23-Feb-2012	1	First release.
03-Dec-2012	2	– Minor text changes in cover page – Added IPAK packages – Added *Section 2.1: Electrical characteristics (curves)* – Updated *Section 5: Packaging mechanical data* – Modified: *note 2* on *Table 2* – Updated: mechanical data for TO-220FP package
02-May-2018	3	The part number STU11N65M5 has been moved to a separate datasheet. Removed maturity status indication from cover page. The document status is production data. Updated title and features in cover page, *Section 1 Electrical ratings*, *Section 2 Electrical characteristics*, *Section 2.1 Electrical characteristics curves* and *Section 4 Package information*. Minor text changes.
17-Jul-2025	4	Updated Section 4: Package information. Minor text changes.

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